

File Index	Comments	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Type #	
0									
1	0			2004/06/23 13:56	USPAT; US-PGPUB; EPO; JPO	(Krul-Johannes.in. Hart-Cornelius-Maria.in. Deleuw-Dagobert-Michel.in. DeHesse-Wilhelm-Bernardus.in. Matters-Marco.in.) and @pd>20040224	0	BRS L1	
2	0			2004/06/23 13:56	DERWENT	(Krul-J.in. Hart-C.in. Deleuw-D.in. DeHesse-W.in. Matters-M.in.) and @pd>20040224	2	BRS L2	
3	0			2004/06/23 13:57	USPAT; US-PGPUB	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (thread strip security forgery authentic\$3) and @pd>20040224	8	BRS L3	
4	0			2004/06/23 13:59	USPAT; US-PGPUB	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (organic polymer) and @pd>20040224	2	BRS L4	
5	0			2004/06/23 13:59	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (security near2 (strip thread)) and @pd>20040224	0	BRS L5	
6	0			2004/06/23 14:00	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) and (security near2 (strip thread)) and @pd>20040224	1	BRS L6	
7	0			2004/06/23 14:03	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (organic near2 polymer) and @pd>20040224	0	BRS L7	
8	0			2004/06/23 14:03	USPAT; US-PGPUB	conduct\$3 near5 (security near2 (strip thread)) and @pd>20040224	1	BRS L8	
9	0			2004/06/23 14:04	USPAT; US-PGPUB	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram) and @pd>20040224	1	BRS L9	

Errors	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Type	Level
0			2004/06/23 14:05	USPAT; US-PGPUB	(conduct\$3 near\$5 (security near\$2 (strip thread))) and (hologram optical\$2 foil kinegram holographic) and @pd>20040224	1	BRS	L10
0			2004/06/23 14:06	USPAT; US-PGPUB	(security near\$2 (strip thread)) same (hologram holographic) and @pd>20040224	2	BRS	L11
0			2004/06/23 14:06	USPAT; US-PGPUB	((paper cardboard currency passport) near\$5 (ic chip semiconductor\$3)) same (noncontact (non adj contact) contactlessly inductive capacitive) and @pd>20040224	4	BRS	L12
0			2004/06/23 14:07	USPAT; US-PGPUB	(ic circuit semiconductive semiconductor) same polyimide same polyaniline and @pd>20040224	1	BRS	L13
0			2004/06/23 14:08	USPAT; US-PGPUB	(organic near\$2 polymer) same polyimide same polyaniline and @pd>20040224	2	BRS	L14
0			2004/06/23 14:09	USPAT; US-PGPUB	(ic circuit semiconductive semiconductor) same (polyimide adj\$10 polyaniline) and @pd>20040224	1	BRS	L15
0			2004/06/23 14:09	USPAT; US-PGPUB	polyimide adj\$10 polyaniline and @pd>20040224	4	BRS	L16
0			2004/06/23 14:10	USPAT; US-PGPUB	(security near\$2 (strip thread)) same (size thickness width thick) and @pd>20040224	8	BRS	L17
0			2004/06/23 14:12	USPAT; US-PGPUB	(banknote\$1 (bank adj note\$1) passport (security adj\$1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconductor) and @pd>20040224	29	BRS	L18

Errors	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Level	Type
0			2004/06/23 14:20	USPAT; US-PGPUB	((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconductor)) not ((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconductor)) and @pd>20040224	0	BRS L19	19
0			2004/06/23 14:21	EPO; JPO; DERWENT; IBM_TDB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconductor) and @pd>20040224	15	BRS L20	20
0			2004/06/23 14:24	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20040224	15	BRS L21	21
0			2004/06/23 14:31	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20040224	1	BRS L22	22
0			2004/06/23 14:32	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20040224	1	BRS L23	23
0			2004/06/23 14:38	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20040224	3	BRS L24	24

Err ors	Comments	Error Definition	Time Stamp	DBs	Search Text	Hits	Type L #
0			2004/06/23 14:39	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor) near5 paper and @pd>20040224	0	BRS L25 0
0			2004/06/23 14:39	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor semiconductor) near5 organic and @pd>20040224	5	BRS L26 5
0			2004/06/23 14:42	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor semiconductor) near5 organic and @pd>20040224	2	BRS L27 2
0			2004/06/23 14:42	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor) near5 paper and @pd>20040224	0	BRS L28 0
0			2004/06/23 14:43	USPAT; US-PGPUB	tag near5 paper near5 (ic chip semiconductor) near5 (antenna coil) and @pd>20040224	0	BRS L29 0
0			2004/06/23 14:43	USPAT; US-PGPUB	paper near5 (ic chip semiconductor) near5 (antenna coil) and @pd>20040224	3	BRS L30 3
0			2004/06/23 14:44	USPAT; US-PGPUB	tag near5 (ic chip semiconductor) near5 (antenna coil) near5 print\$3 and @pd>20040224	1	BRS L31 1
0			2004/06/23 14:45	USPAT; US-PGPUB	(340/572.8.ccls. 257/774.ccls. 257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.) and @pd>20040224	508	BRS L32 508

Errors	Error Definition	Comments	Time Stamp	Dbs	Search Text	Hits	Typ L #
0					(Kru1-Johannes.in. Hart-Cornelius-Maria.in. Deleeuw-Dagobert-Michel.in. DeHesse-Wilhelm-Bernardus.in. Matters-Marco.in.) and @pd>20040623	0	BRS L1
0			2004/07/01 15:19	USPAT; US-PGPUB; EPO, JPO	(Kru1-J.in. Hart-C.in. Deleeuw-D.in. DeHesse-W.in. Matters-M.in.) and @pd>20040623	0	BRS L2
0			2004/07/01 15:20	USPAT; US-PGPUB	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (thread strip security forgery authentic\$3) and @pd>20040623	0	BRS L3
0			2004/07/01 15:22	USPAT; US-PGPUB	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (organic polymer) and @pd>20040623	0	BRS L4
0			2004/07/01 15:23	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (security near2 (strip thread)) and @pd>20040623	0	BRS L5
0			2004/07/01 15:23	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) and (security near2 (strip thread)) and @pd>20040623	0	BRS L6
0			2004/07/01 15:23	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (organic near2 polymer) and @pd>20040623	0	BRS L7
0			2004/07/01 15:24	USPAT; US-PGPUB	conduct\$3 near5 (security near2 (strip thread)) and @pd>20040623	0	BRS L8
0			2004/07/01 15:24	USPAT; US-PGPUB	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram) and @pd>20040623	0	BRS L9

Errors	Error Definition	Comments	Time Stamp	Dbs	Search Text	Hits	Type	Level
0			2004/07/01 15:24	USPAT; US-PGPUB	(conduct\$3 near5 (security near2 (strip thread)) and (hologram optical\$2 foil kinegram holographic) and @pd>20040623	0	BRS	L10
0			2004/07/01 15:25	USPAT; US-PGPUB	(security near2 (strip thread)) same (hologram holographic) and @pd>20040623	1	BRS	L11
0			2004/07/01 15:25	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (noncontact (non adj contact) contactlessly inductive capacitive) and @pd>20040623	0	BRS	L12
0			2004/07/01 15:33	USPAT; US-PGPUB	(ic circuit semiconductive semiconductor) same polyimide same polyaniline and @pd>20040623	1	BRS	L13
0			2004/07/01 15:34	USPAT; US-PGPUB	(organic near2 polymer) same polyimide same polyaniline and @pd>20040623	0	BRS	L14
0			2004/07/01 15:34	USPAT; US-PGPUB	(ic circuit semiconductive semiconductor) same (polyimide adj10 polyaniline) and @pd>20040623	0	BRS	L15
0			2004/07/01 15:34	USPAT; US-PGPUB	polyimide adj10 polyaniline and @pd>20040623	0	BRS	L16
0			2004/07/01 15:35	USPAT; US-PGPUB	(security near2 (strip thread)) same (size thickness width thick) and @pd>20040623	0	BRS	L17
0			2004/07/01 15:35	USPAT; US-PGPUB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20040623	2	BRS	L18

Errors	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Level	Type
0								
0			2004/07/01 15:41	USPAT; US-PGPUB	((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconducting)) not ((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting)) and @pd>20040623	0	BRS	L20
0			2004/07/01 15:41	EPO; JPO; DERWENT; IBM_TDB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20040623	0	BRS	L21
0			2004/07/01 15:42	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20040623	3	BRS	L22
0			2004/07/01 15:46	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20040623	0	BRS	L23
0			2004/07/01 15:46	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20040623	0	BRS	L24
0			2004/07/01 15:47	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20040623	0	BRS	L25

Errors	Error Definition	Comments	Time Stamp	Dbs	Search Text	Hits	Type	Ln #
0						(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor) near5 paper and @pd>20040623	BRS	L260
0			2004/07/01 15:47	USPAT; US-PGPUB		(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor @pd>20040623	BRS	L271
0			2004/07/01 15:48	EPO; JPO; DERWENT; IBM_TDB		(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor @pd>20040623	BRS	L280
0			2004/07/01 15:48	EPO; JPO; DERWENT; IBM_TDB		(flexible flexibility bend\$4) near5 (ic integrated adj circuit\$1) semiconductor) near5 paper and @pd>20040623	BRS	L290
0			2004/07/01 15:48	USPAT; US-PGPUB		tag near5 paper near5 (ic chip semiconductor) near5 (antenna coil) and @pd>20040623	BRS	L300
0			2004/07/01 15:49	USPAT; US-PGPUB		paper near5 (ic chip semiconductor) near5 (antenna coil) and @pd>20040623	BRS	L311
0			2004/07/01 15:49	USPAT; US-PGPUB		tag near5 (ic chip semiconductor) near5 (antenna coil) near5 print\$3 and @pd>20040623	BRS	L320
0			2004/07/01 15:50	USPAT; US-PGPUB		(340/572.8.ccls. 257/774.ccls. 257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.) and @pd>20040623	BRS	L3352